

# D1FT6A

Schottky Barrier Diodes  
60V, 3A

## Feature

- Small SMD
- High Recovery Speed
- $T_j=175^\circ\text{C}$
- Ultra low  $I_R$
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

## OUTLINE

Package (House Name): 1F  
Package (JEDEC Code): DO-214AC



## Equivalent circuit



## Absolute Maximum Ratings (unless otherwise specified : $T_l=25^\circ\text{C}$ )

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	$T_{stg}$		-55 to 175	°C
Junction temperature	$T_j$		-55 to 175	°C
Repetitive peak reverse voltage	$V_{RRM}$		60	V
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, $T_l=125^\circ\text{C}$	3	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On alumina substrate, $T_a=25^\circ\text{C}$ ※	2.13	A
Average forward current	$I_F(AV)$	50Hz sine wave, Resistance load, On glass-epoxy substrate, $T_a=25^\circ\text{C}$ ※	1.56	A
Surge forward current	$I_{FSM}$	50Hz sine wave, Non-repetitive, 1cycle, Peak value, $T_j=25^\circ\text{C}$	90	A

※ : See the original Specifications

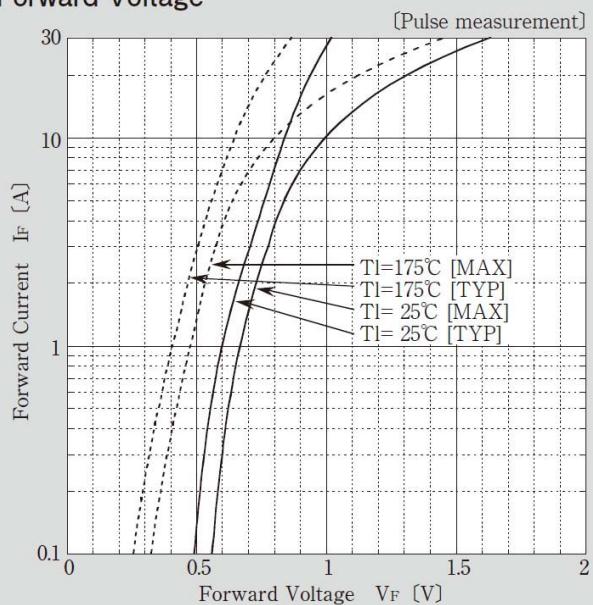
**Electrical Characteristics** (unless otherwise specified : Tl=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Forward voltage	$V_F$	IF=3A, Pulse measurement			0.78	V
Forward voltage	$V_F$	IF=1A, Pulse measurement			0.67	V
Reverse current	$I_R$	VR=60V, Pulse measurement			0.008	mA
Total capacitance	$C_t$	f=1MHz, VR=10V		78		pF
Thermal resistance	$R_{th(j-l)}$	Junction to lead			23	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On alumina substrate	※		108	°C/W
Thermal resistance	$R_{th(j-a)}$	Junction to ambient, On glass-epoxy substrate	※		157	°C/W

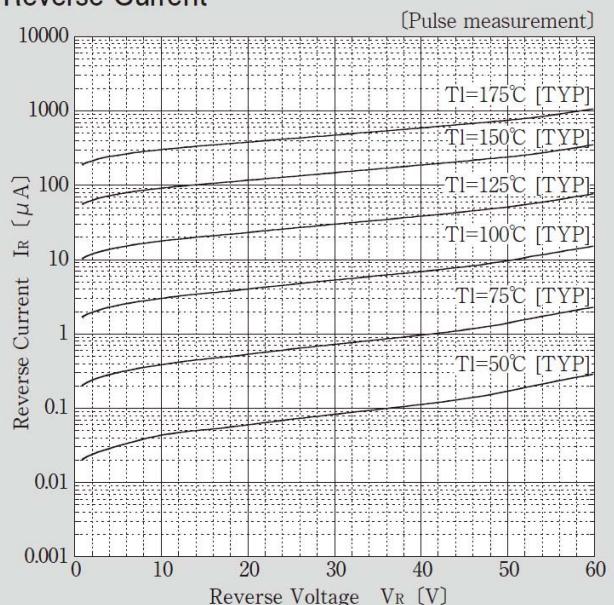
※ :See the original Specifications

## CHARACTERISTIC DIAGRAMS

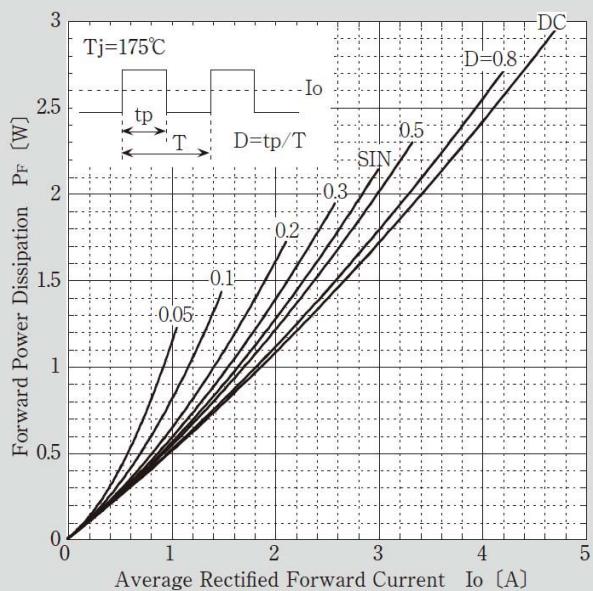
Forward Voltage



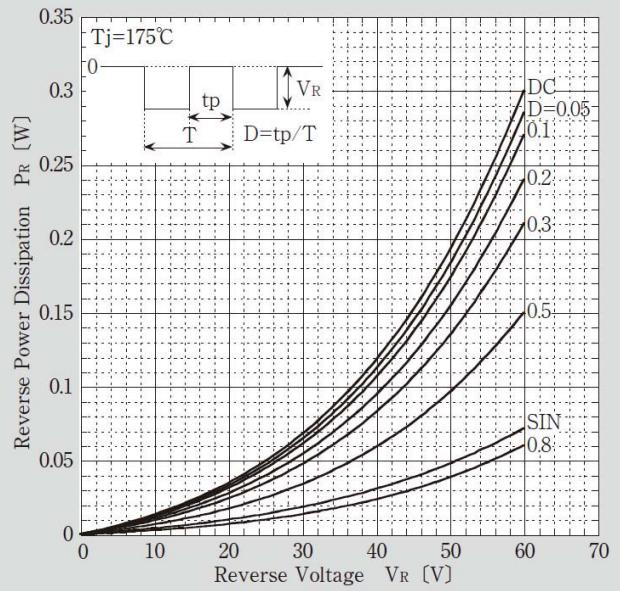
Reverse Current

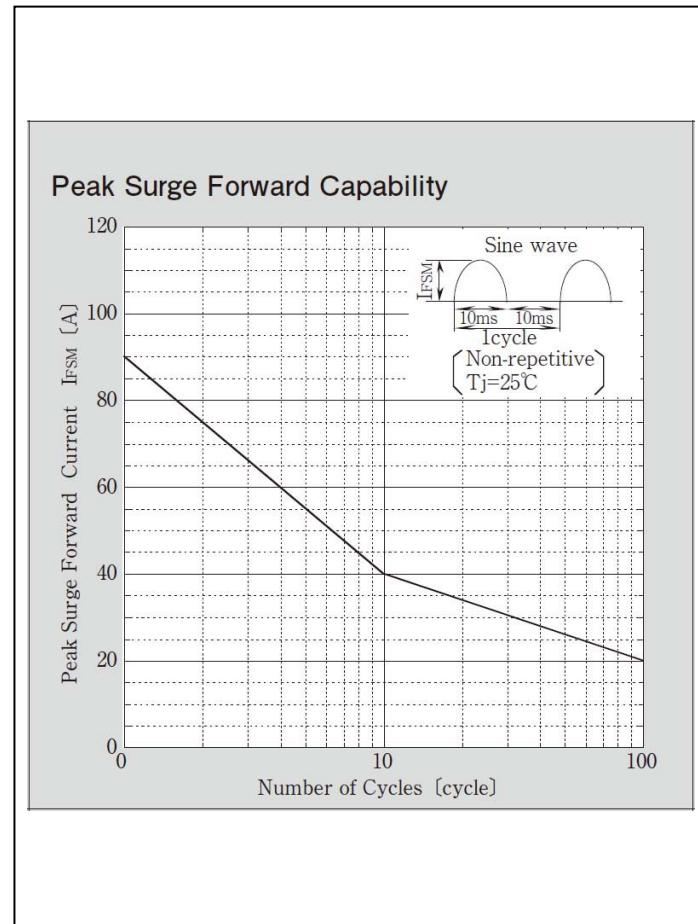
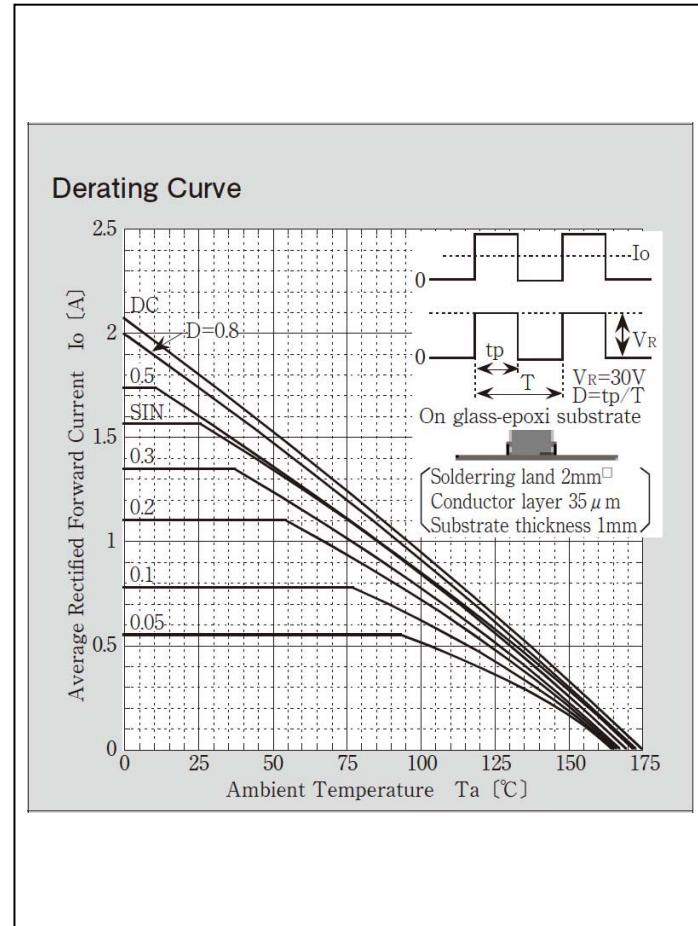
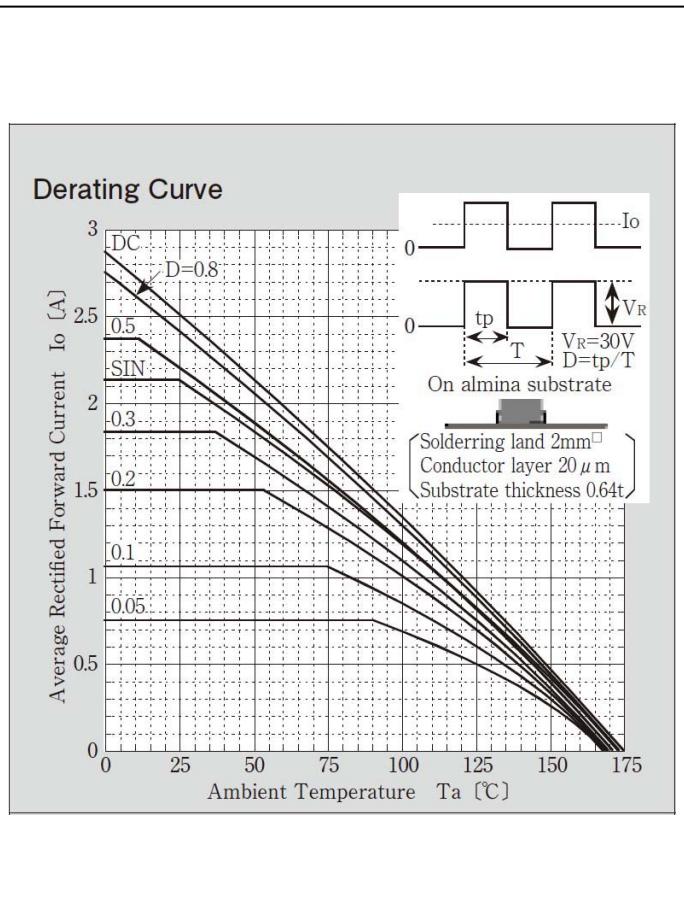
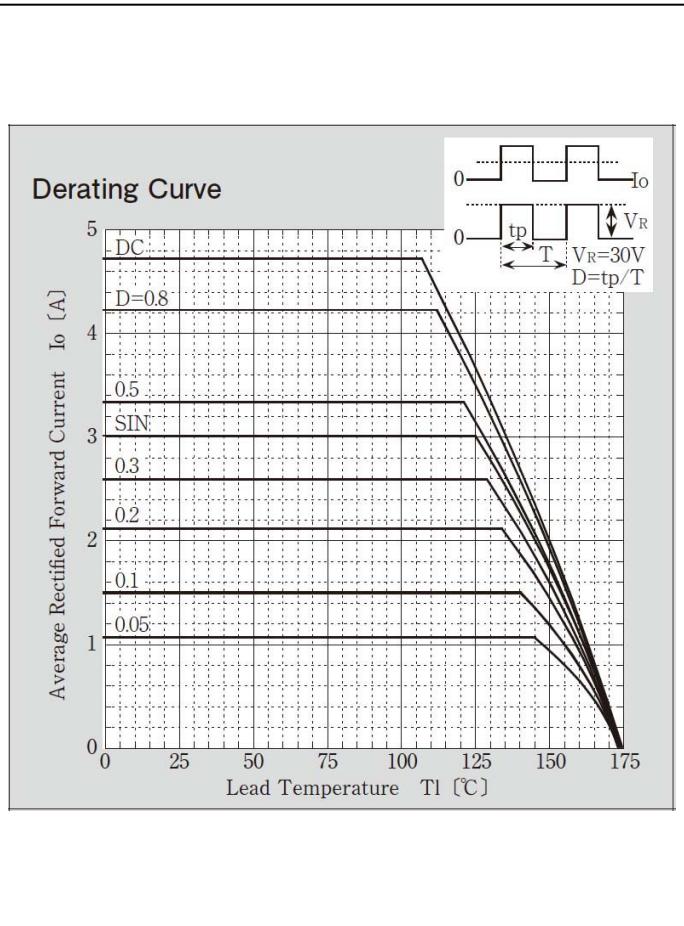


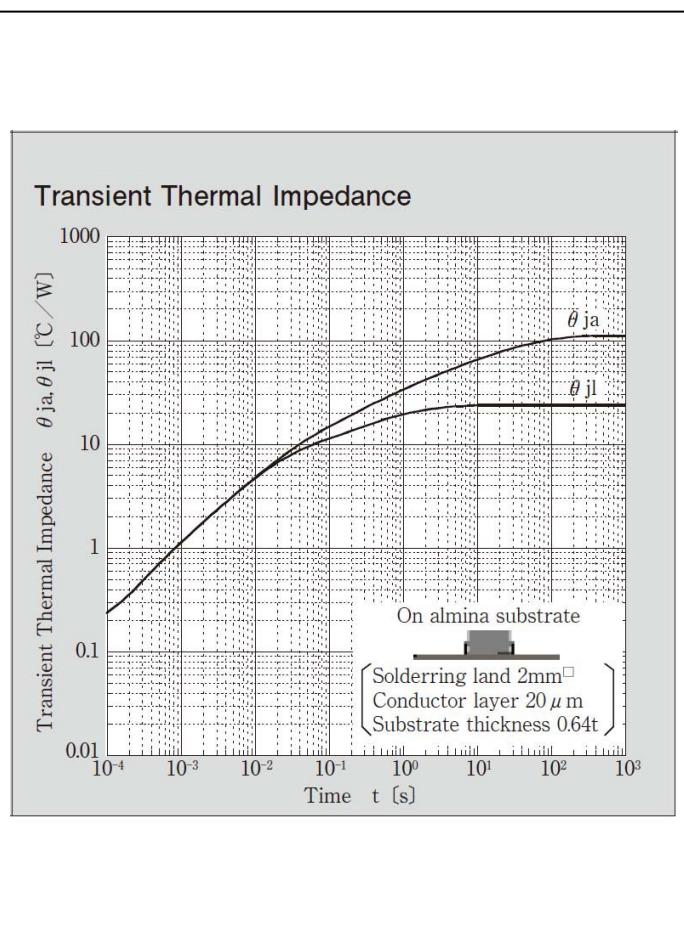
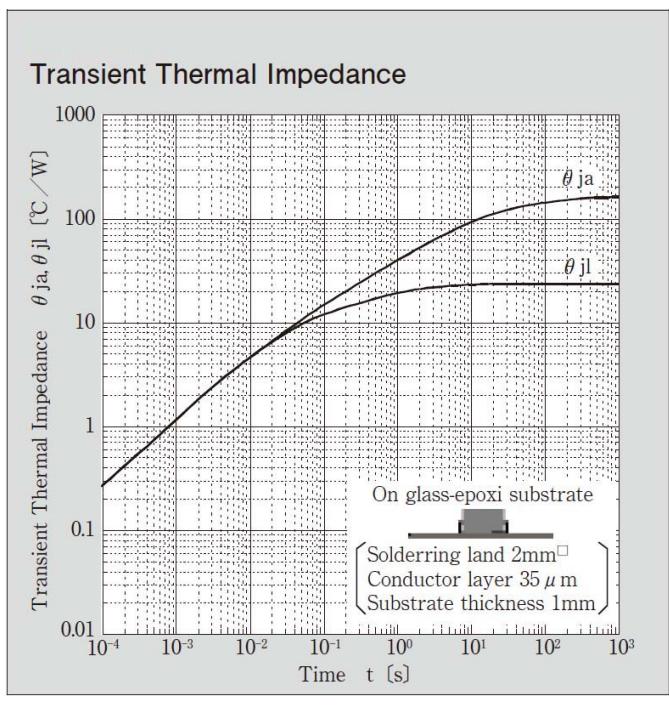
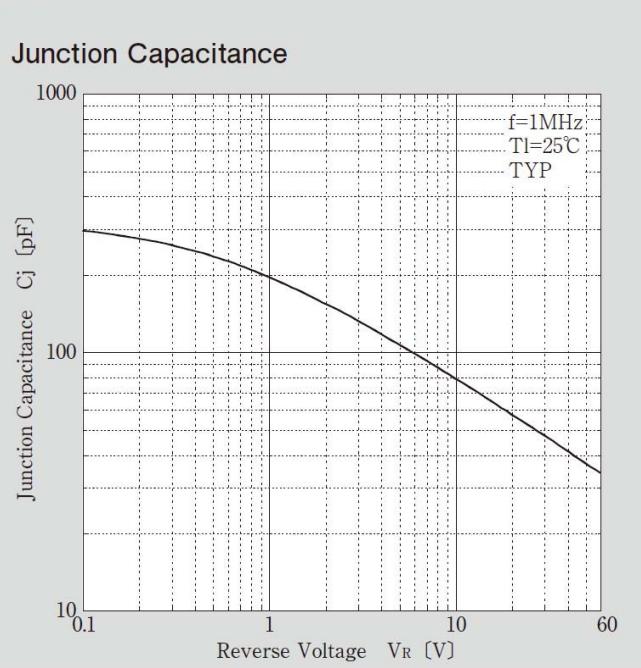
Forward Power Dissipation



Reverse Power Dissipation







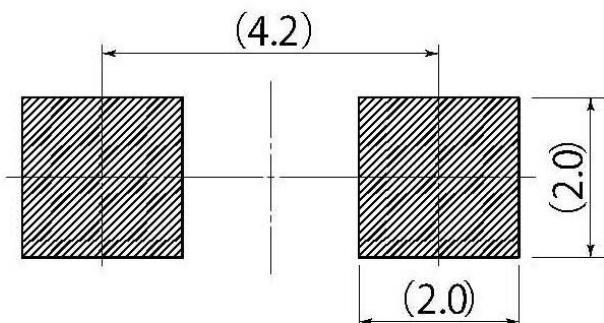
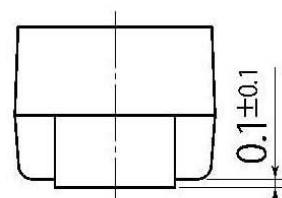
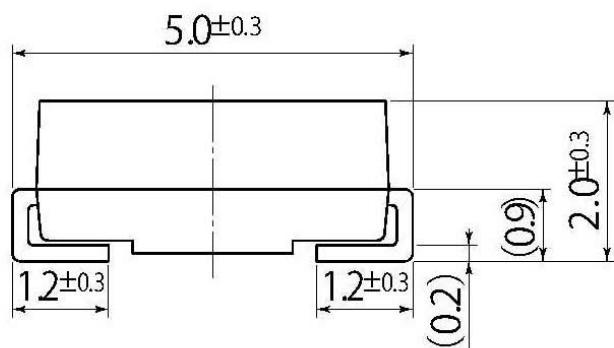
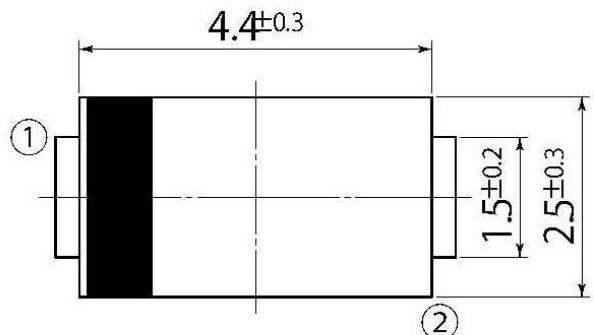
## Outline Dimensions

unit:mm

scale: 10/1

B3

JEDEC Code	DO-214AC
JEITA Code	—
House Name	1F, CF



Referential Soldering Pad

- Optimize soldering pad to the board design and soldering condition.

## Notes

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